

TSD60R380S1

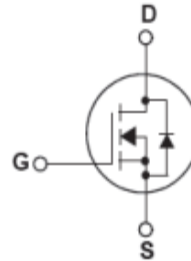
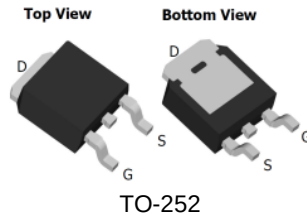
600V 10.6A N-Channel SJ-MOSFET

General Description

Truesemi SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance. This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.

Features

- 650V @TJ = 150 °C
- Typ. RDS(on) = 0.34Ω
- Ultra Low gate charge (typ. Qg = 38nC)
- 100% avalanche tested



Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source Voltage	600	V
I _D	Drain Current -Continuous (TC = 25°C) -Continuous (TC = 100°C)	10.6 6.7	A
I _{DM}	Drain Current – Pulsed (Note 1)	32	A
V _{GSS}	Gate-Source voltage	±30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	210	mJ
I _{AR}	Avalanche Current (Note 1)	1.8	A
E _{AR}	Repetitive Avalanche Energy (Note 1)	0.32	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	15	V/ns
P _D	Power Dissipation (TC = 25°C) -Derate above 25°C	83 1.5	W W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	°C

* Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	Value	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	1.5	°C/W
R _{θCS}	Thermal Resistance, Case-to-Sink Typ.	0.5	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	62	°C/W

Electrical Characteristics TC = 25℃ unless otherwise noted

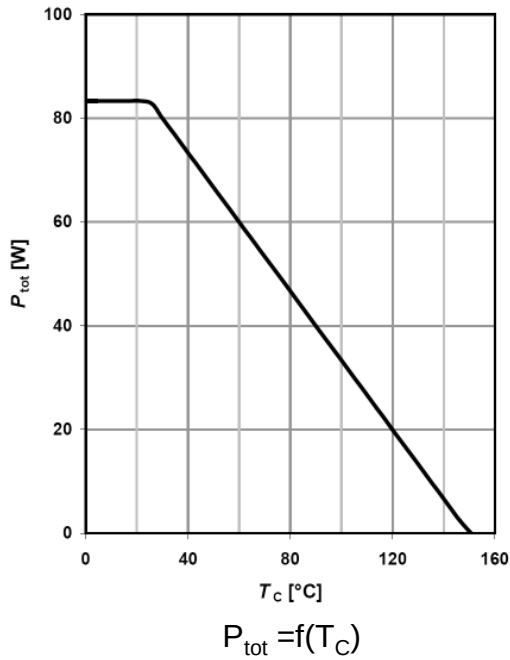
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA, T _J = 25℃	600	--	--	V
		V _{GS} = 0V, I _D = 250μA, T _J = 150℃	--	650	--	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25℃	--	0.6	--	V/℃
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 600V, V _{GS} = 0V -T _J = 150℃	--	-- 10	1 --	μA μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V	--	--	-100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.5	--	4.5	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 5.5A	--	0.34	0.38	Ω
g _{FS}	Forward Trans conductance	V _{DS} = 40V, I _D = 5.5A (Note 4)	--	16	--	S
R _g	Gate resistance	f=1 MHz, open drain	--	3	--	Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	--	680	--	pF
C _{oss}	Output Capacitance		--	240	--	pF
C _{rss}	Reverse Transfer Capacitance		--	7	--	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 400V, I _D = 5.5A R _G = 20Ω(Note 4, 5)	--	15	--	ns
t _r	Turn-On Rise Time		--	10	--	ns
t _{d(off)}	Turn-Off Delay Time		--	110	--	ns
t _f	Turn-Off Fall Time		--	9	--	ns
Q _g	Total Gate Charge	V _{DS} = 480V, I _D = 5.5A V _{GS} = 10V (Note 4, 5)	--	38	--	nC
Q _{gs}	Gate-Source Charge		--	4	--	nC
Q _{gd}	Gate-Drain Charge		--	4.2	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	11	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	30	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _F = 5.5A	--	0.9	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _F = 5.5A di _F /dt =100A/μs (Note 4)	--	270	--	ns
Q _{rr}	Reverse Recovery Charge		--	3.3	--	μC

NOTES:

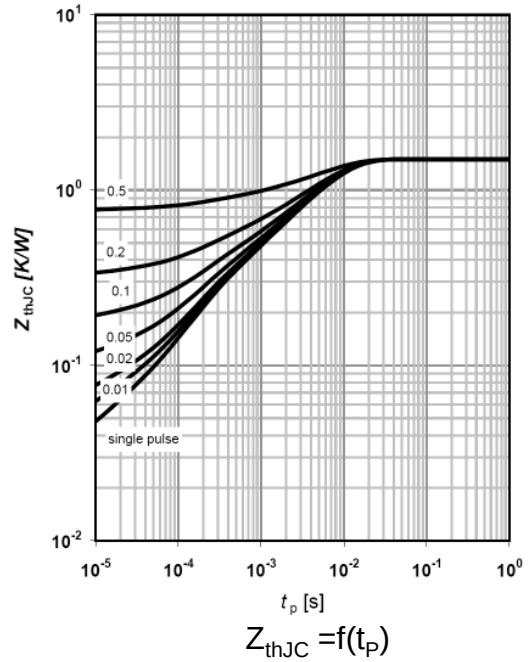
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_{AS}=1.8A, V_{DD}=50V$, Starting $T_J=25^\circ C$
3. $I_{SD}\leq 10.6A, di/dt \leq 200A/\mu s, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ C$
4. Pulse Test: Pulse width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

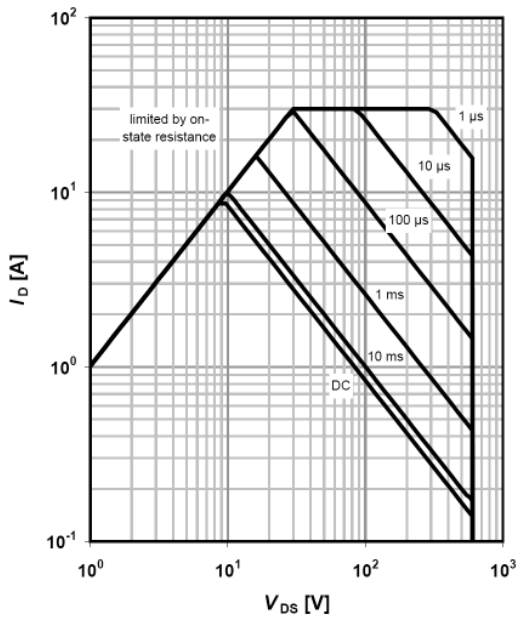
Power dissipation



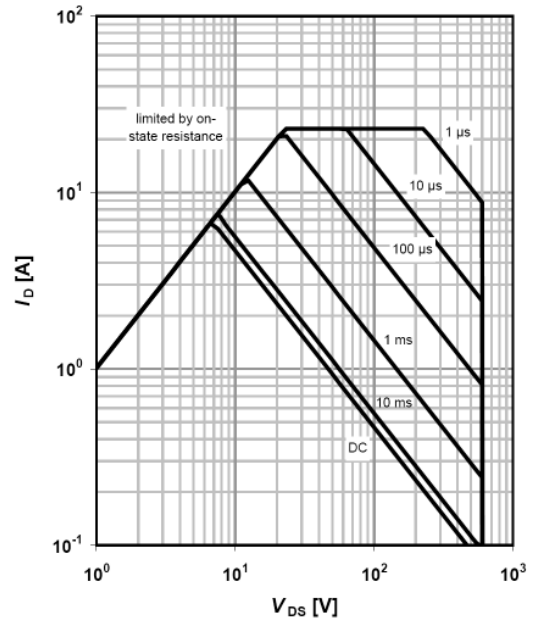
Max. transient thermal impedance



Safe operating area $T_c = 25^\circ\text{C}$

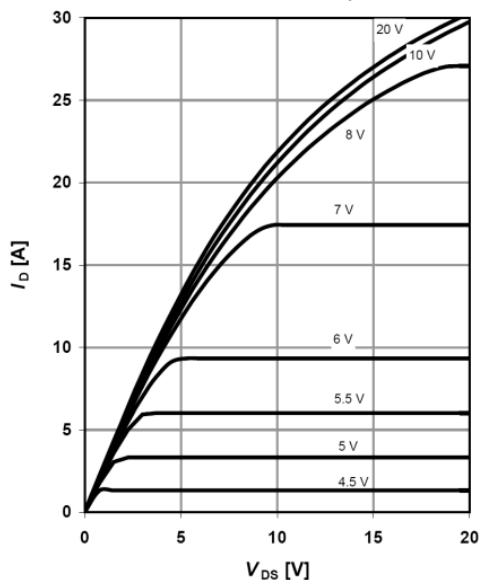


Safe operating area $T_c = 80^\circ\text{C}$



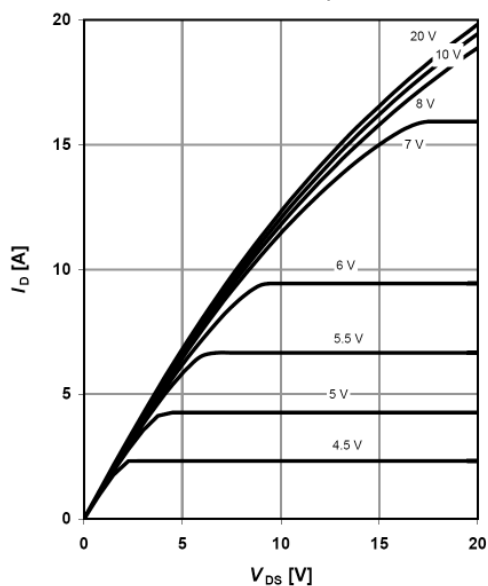
Typical Performance Characteristics

Typ. output characteristics $T_j=25^\circ\text{C}$



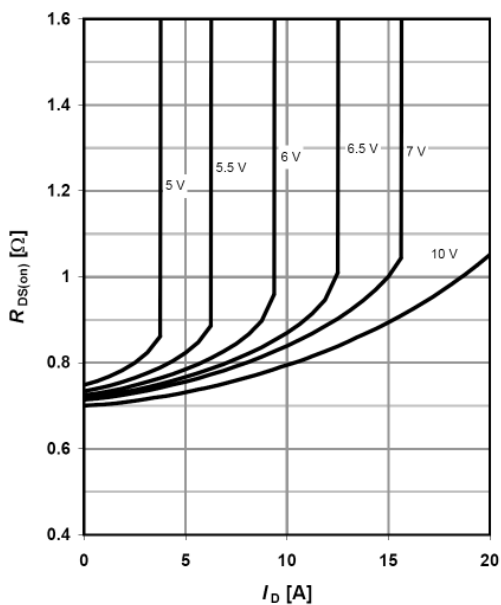
$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$$

Typ. output characteristics $T_j=125^\circ\text{C}$



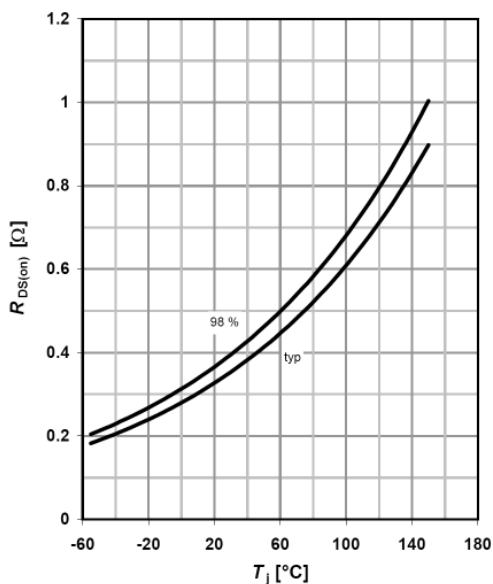
$$I_D = f(V_{DS}); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$$

Typ. drain-source on-state resistance



$$R_{DS(on)} = f(I_D); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$$

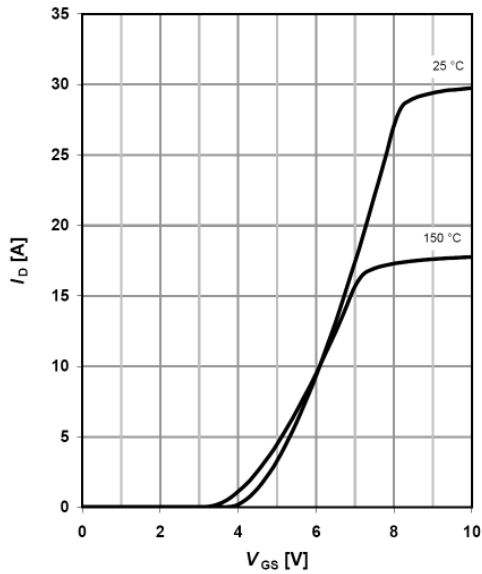
Typ. drain-source on-state resistance



$$R_{DS(on)} = f(T_j); I_D = 3.8\text{ A}; V_{GS} = 10\text{ V}$$

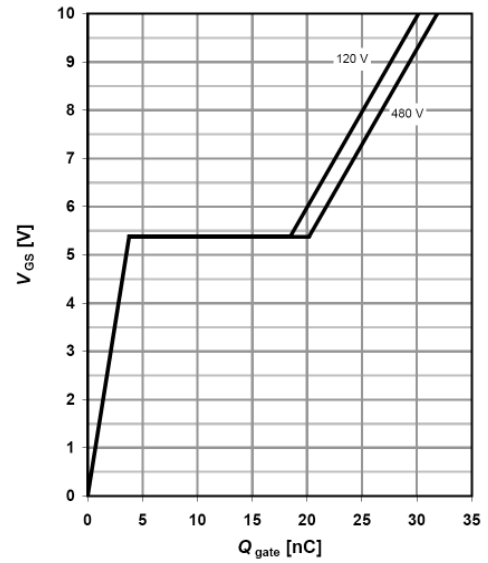
Typical Performance Characteristics

Typ. transfer characteristics



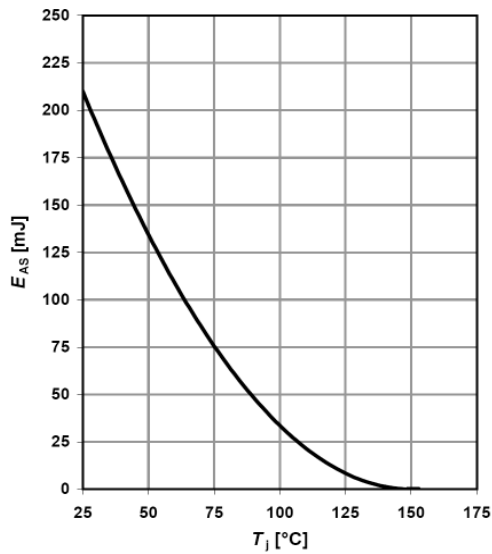
$$I_D = f(V_{GS}); V_{DS} = 20V$$

Typ. gate charge



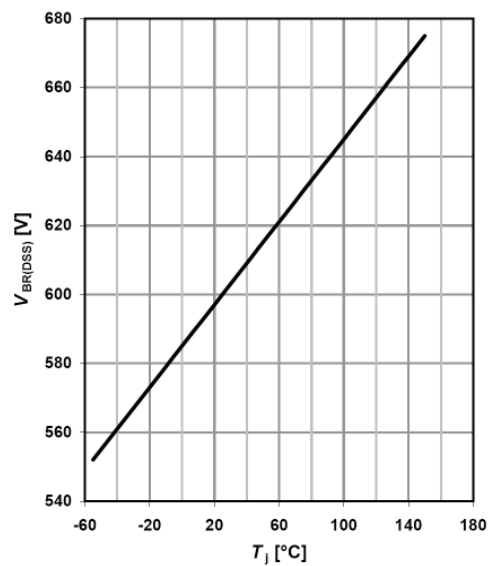
$$V_{GS} = f(Q_g), I_D = 4.8 A \text{ pulsed}$$

Avalanche energy



$$E_{AS} = f(T_j); I_D = 1.8 A; V_{DD} = 50 V$$

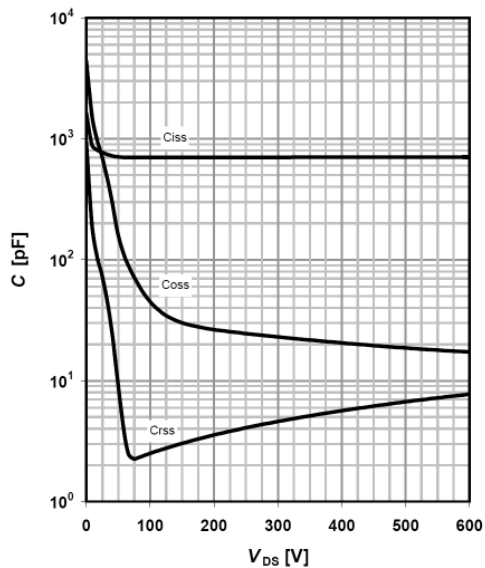
Drain-source breakdown voltage



$$V_{BR(DSS)} = f(T_j); I_D = 0.25 mA$$

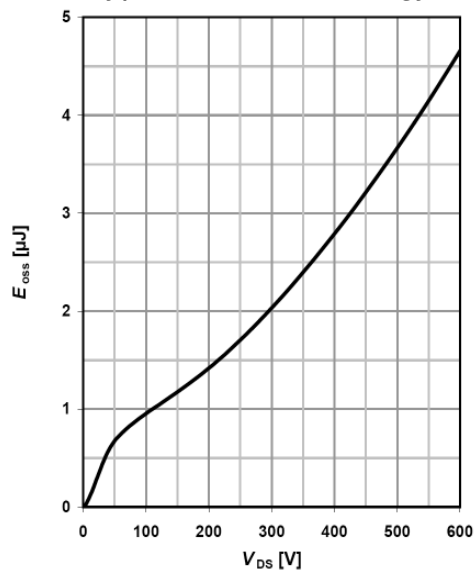
Typical Performance Characteristics

Typ. capacitances



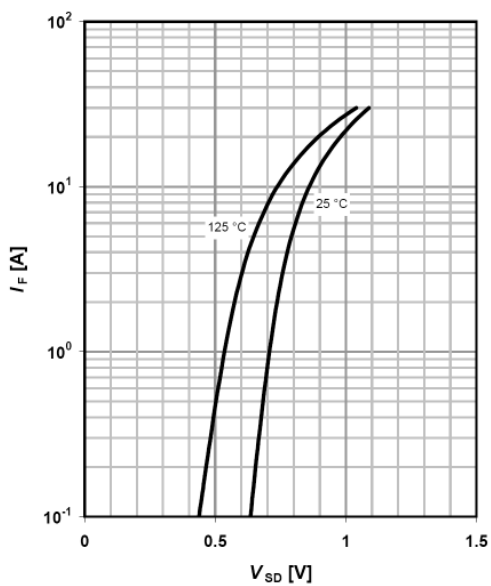
$$C=f(V_{DS}); V_{GS}=0 \text{ V}; f=1 \text{ MHz}$$

Typ. C_{oss} stored energy



$$E_{OSS}=f(V_{DS})$$

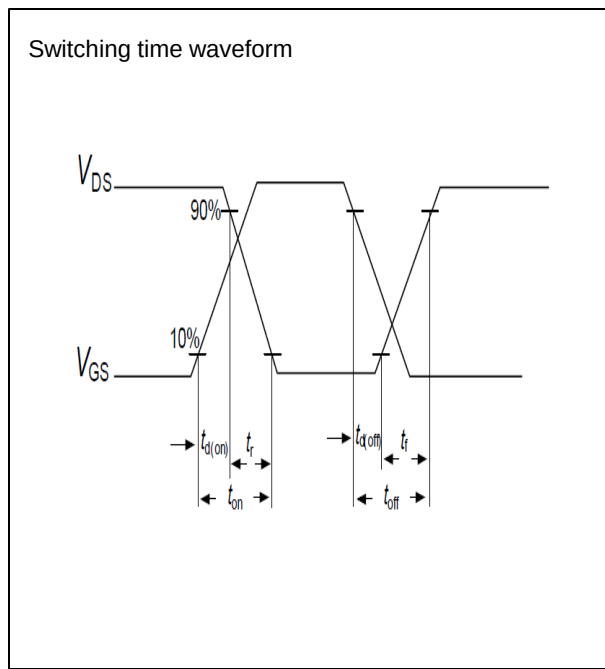
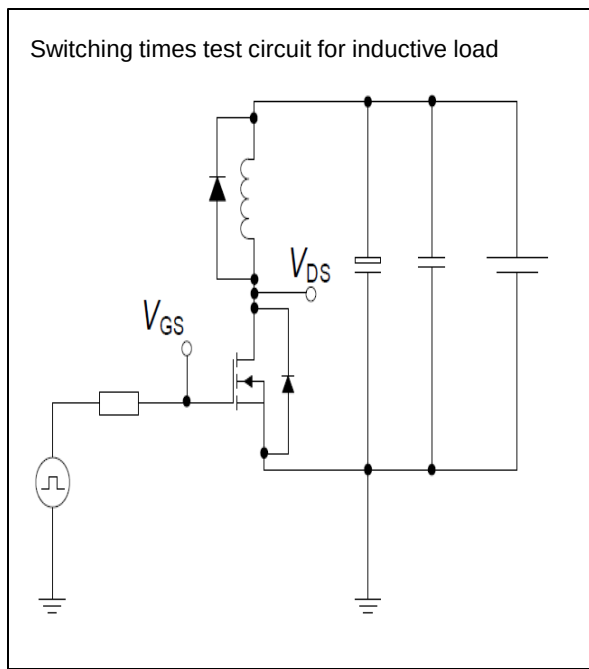
Forward characteristics of reverse diode



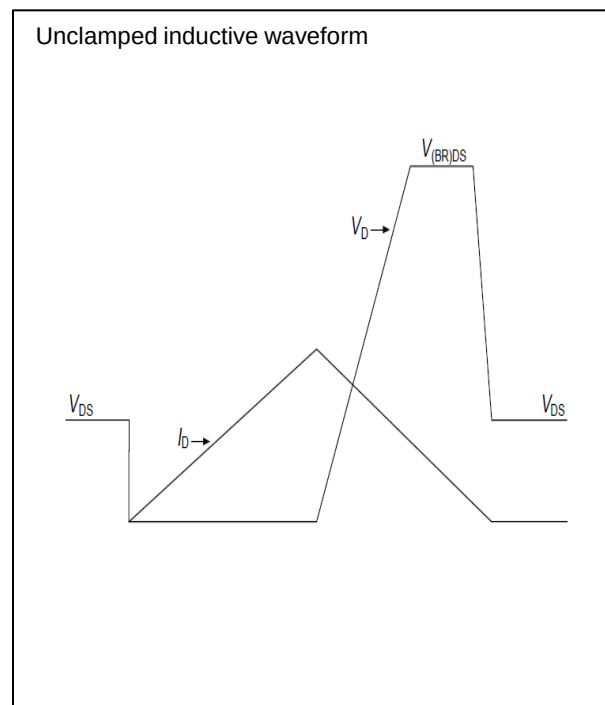
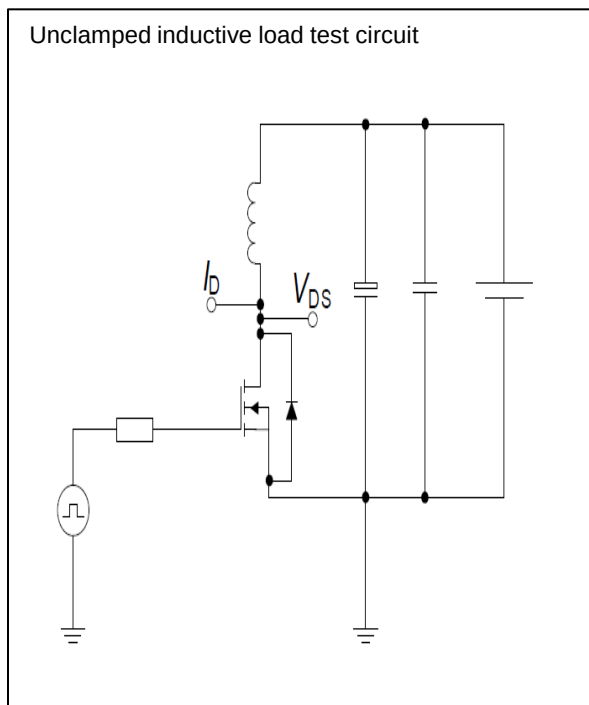
$$I_F=f(V_{SD}); \text{ parameter: } T_j$$

Test circuits

Switching times test circuit and waveform for inductive load



Unclamped inductive load test circuit and waveform



TSD60R380S1 600V 10.6A N-Channel SJ-MOSFET

Test circuit for diode characteristics

